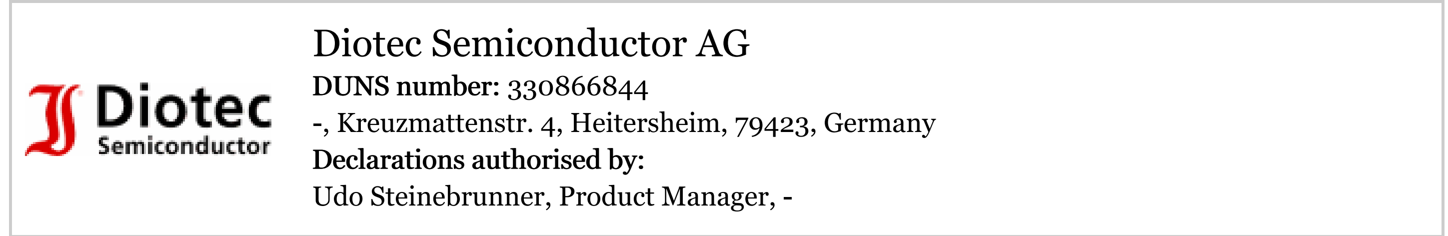
BOMcheck.net

Full Material Declaration for attached parts list

Report generated: 03 February 2026, 13:50 GMT



Diotec Semiconductor AG
DUNS number: 330866844
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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 02 January 2015 [Approved on 03 February 2026, 13:49 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.89%	Silicon	7440-21-3	100%
Die attach	Lead and Lead alloys	1.67%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	47.95%	Carbon black	1333-86-4	0.5%
			ZINC BORATE	1332-07-6	5%
			Phenol, polymer with formaldehyde	9003-35-4	10%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	12%
			Quartz sand	60676-86-0	72.5%
Leadfinish	Tin plating	0.21%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	48.28%	COPPER, ELEMENTAL	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DIL-SLIM/SO-DIL-SLIM-HF	Bridge Rectifier Dual Inline	0.2515	g